PATENT

MAY 2 8 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of   :

Eiji HAYASHI   :

Serial No.: 09/810,454   :   Group Art Unit: 1725

                                                        :

Filed: March 19, 2001   :   Examiner: Jonathan J. Johnson

                                                        :

For: FLIP CHIP BONDING METHOD

THE COMMISSIONER FOR PATENTS AND TRADEMARKS
Washington, DC 20231

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MAY 2 9 2002

Dear Sir:

TC 1700

Transmitted herewith is an Amendment in the above identified application.
☒   No additional fee is required.
☐   Applicant is entitled to small entity status under 37 CFR 1.27
☐   Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	2	20	0	$18.00 =	$0.00
Independent Claims	1	3	0	$84.00 =	$0.00
	Multiple claims newly presented				$0.00
	Fee for extension of time				$0.00
					$0.00
			Total of Above Calculations		$0.00

☐   Please charge my Deposit Account No. <u>500417</u> in the amount of $0.00. An additional copy of this transmittal sheet is submitted herewith.

☒   The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.
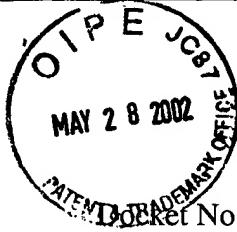
Respectfully submitted,

MCDERMOTT, WILL & EMERY

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<!-- OIPE stamp: MAY 28 2002 PATENT AND TRADEMARK OFFICE -->

Docket No.: 50088-056

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:
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Eiji HAYASHI	:
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Serial No.: 09/810,454	: Group Art Unit: 1725
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AMENDMENT

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Commissioner for Patents
Washington, DC 20231

MAY 2 9 2002

TC 1700

Sir:

The following Amendments and Remarks are filed in response to the Office

Action dated February 26, 2002.

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 1, line 17, with the following

rewritten paragraph:

--However, the conventional flip chip bonding method uses flux. Flux removes

oxide films on surfaces of solder bumps and to facilitate connections by solder. However, if

the quantity of the flux is not optimized or a step of cleaning is not controlled, there are

problems that the flux is left as propellant fouling after the step of cleaning, and the

propellant fouling prevents a sealing resin from being injected in a later step, whereby voids

are induced, yield is dropped, and reliability is spoiled.--

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